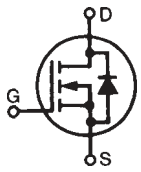
IXYS

Polar™ HiPerFET™ Power MOSFET

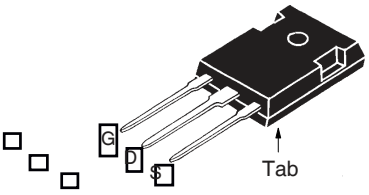
IXFH120N20P
IXFK120N20P

V_{DSS} = 200V
I_{D25} = 120A
$R_{DS(on)}$ ≤ 22mΩ
t_{rr} ≤ 200ns

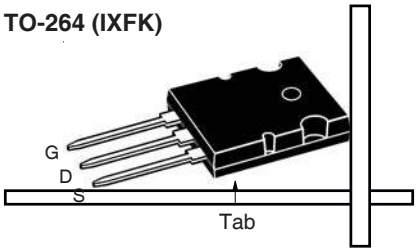
N-Channel Enhancement Mode
Avalanche Rated
Fast Intrinsic Diode



TO-247 (IXFH)



TO-264 (IXFK)



G = Gate D = Drain
S = Source Tab = Drain

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 175°C	200	V
V_{DGR}	T_J = 25°C to 175°C, R_{GS} = 1MΩ	200	V
V_{GSS}	Continuous	± 20	V
V_{GSM}	Transient	± 30	V
I_{D25}	T_C = 25°C	120	A
I_{LRMS}	Lead Current Limit, RMS	75	A
I_{DM}	T_C = 25°C, Pulse Width Limited by T_{JM}	300	A
I_A	T_C = 25°C	60	A
E_{AS}	T_C = 25°C	2	J
P_D	T_C = 25°C	714	W
dV/dt	$I_S \le I_{DM}$, $V_{DD} \le V_{DSS}$, $T_J \le 175°C$	10	V/ns
T_J		-55 ... +175	°C
T_{JM}		175	°C
T_{stg}		-55 ... +175	°C
T_L	1.6mm (0.062 in.) from Case for 10s	300	°C
T_{SOLD}	Plastic Body for 10s	260	°C
M_d	Mounting Torque	1.13/10	Nm/lb.in.
Weight	TO-247	6	g
	TO-264	10	g

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
BV_{DSS}	V_{GS} = 0V, I_D = 250μA	200			V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, I_D = 4mA	2.5		5.0	V
I_{GSS}	V_{GS} = ± 20V, V_{DS} = 0V			± 200	nA
I_{DSS}	$V_{DS} = V_{DSS}$, V_{GS}= 0V			25	μA
	T_J = 150°C			500	μA
$R_{DS(on)}$	V_{GS} = 10V, $I_D = 0.5 \bullet I_{D25}$, Note 1			22	mΩ

Features

- International Standard Packages
- Avalanche Rated
- Fast Intrinsic Diode
- Low Q_G
- Low $R_{DS(on)}$
- Low Drain-to-Tab Capacitance
- Low Package Inductance

Advantages

- Easy to Mount
- Space Savings

Applications

- DC-DC Coverters
- Battery Chargers
- Switch-Mode and Resonant-Mode Power Supplies
- DC Choppers
- AC and DC Motor Drives
- Uninterrupted Power Supplies
- High Speed Power Switching Applications

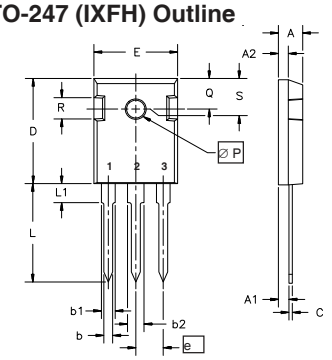
Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	V_{DS} = 10V, I_D = 0.5 • I_{D25}, Note 1	40	63		S
C_{iss}	V_{GS} = 0V, V_{DS} = 25V, f = 1MHz		6000		pF
C_{oss}			1300		pF
C_{rss}			265		pF
$t_{d(on)}$	**Resistive Switching Times**		30		ns
t_r	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		35		ns
$t_{d(off)}$	R_G = 3.3Ω (External)		100		ns
t_f			31		ns
$Q_{g(on)}$	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		152		nC
Q_{gs}			40		nC
Q_{gd}			75		nC
R_{thJC}				0.21	°C/W
R_{thCS}	TO-247		0.21		°C/W
	TO-264		0.15		°C/W

Source-Drain Diode

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
I_S	V_{GS} = 0V			120	A
I_{SM}	Repetitive, Pulse Width Limited by T_{JM}			300	A
V_{SD}	I_F = I_S , V_{GS} = 0V, Note 1			1.5	V
t_{rr}	I_F = 25A, -di/dt = 100A/μs		100	200	ns
Q_{RM}	V_R = 100V, V_{GS} = 0V		0.4		μC
I_{RM}			6.0		A

Note 1. Pulse test, t ≤ 300μs, duty cycle, d ≤ 2%.

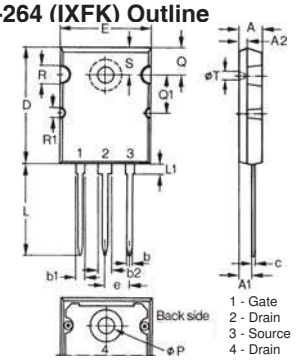
TO-247 (IXFH) Outline



Terminals: 1 - Gate 2 - Drain
3 - Source

Dim.	Millimeter Min.	Max.	Inches Min.	Max.
A	4.7	5.3	.185	.209
A_1	2.2	2.54	.087	.102
A_2	2.2	2.6	.059	.098
b	1.0	1.4	.040	.055
b_1	1.65	2.13	.065	.084
b_2	2.87	3.12	.113	.123
C	.4	.8	.016	.031
D	20.80	21.46	.819	.845
E	15.75	16.26	.610	.640
e	5.20	5.72	0.205	0.225
L	19.81	20.32	.780	.800
L1		4.50		.177
ØP	3.55	3.65	.140	.144
Q	5.89	6.40	0.232	0.252
R	4.32	5.49	.170	.216
S	6.15 BSC		242 BSC	

TO-264 (IXFK) Outline



1 - Gate
2 - Drain
3 - Source
4 - Drain

Dim.	Millimeter Min.	Max.	Inches Min.	Max.
A	4.82	5.13	.190	.202
A1	2.54	2.89	.100	.114
A2	2.00	2.10	.079	.083
b	1.12	1.42	.044	.056
b1	2.39	2.69	.094	.106
b2	2.90	3.09	.114	.122
c	0.53	0.83	.021	.033
D	25.91	26.16	1.020	1.030
E	19.81	19.96	.780	.786
e	5.46 BSC		.215 BSC	
J	0.00	0.25	.000	.010
K	0.00	0.25	.000	.010
L	20.32	20.83	.800	.820
L1	2.29	2.59	.090	.102
P	3.17	3.66	.125	.144
Q	6.07	6.27	.239	.247
Q1	8.38	8.69	.330	.342
R	3.81	4.32	.150	.170
R1	1.78	2.29	.070	.090
S	6.04	6.30	.238	.248
T	1.57	1.83	.062	.072

Fig. 1. Output Characteristics @ 25ºC

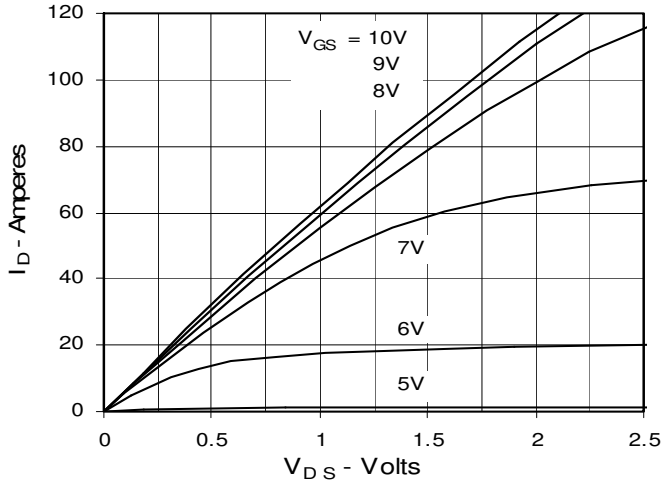


Fig. 2. Extended Output Characteristics @ 25ºC

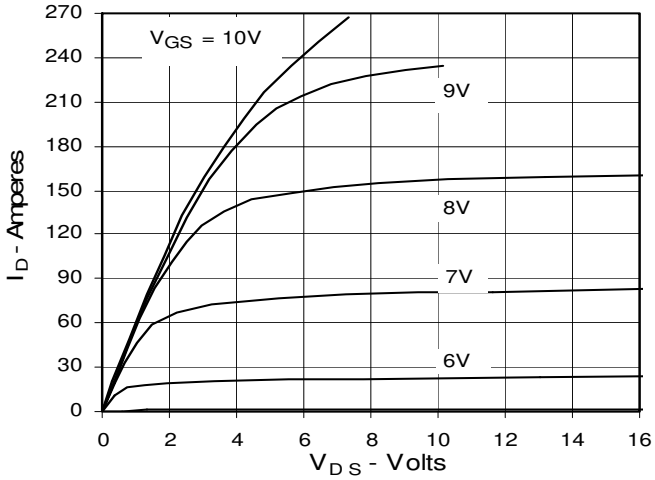


Fig. 3. Output Characteristics @ 150ºC

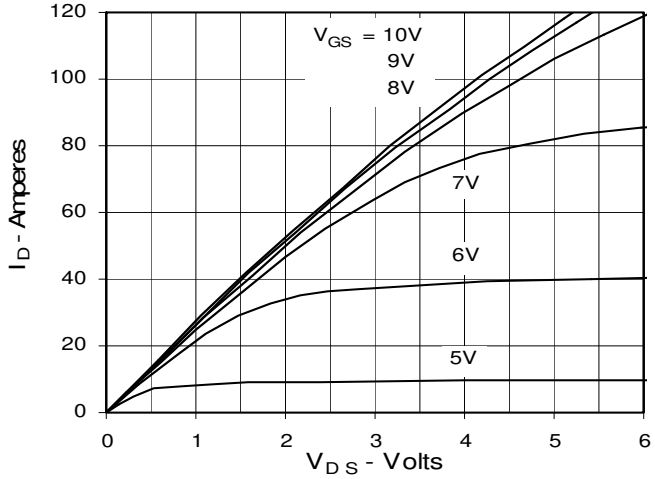


Fig. 4. $R_{DS(on)}$ Normalized to 0.5 I_{D25} Value vs. Junction Temperature

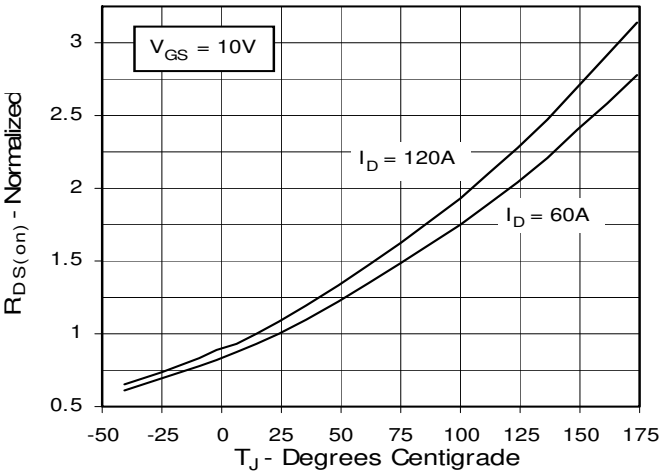


Fig. 5. $R_{DS(on)}$ Normalized to 0.5 I_{D25} Value vs. Drain Current

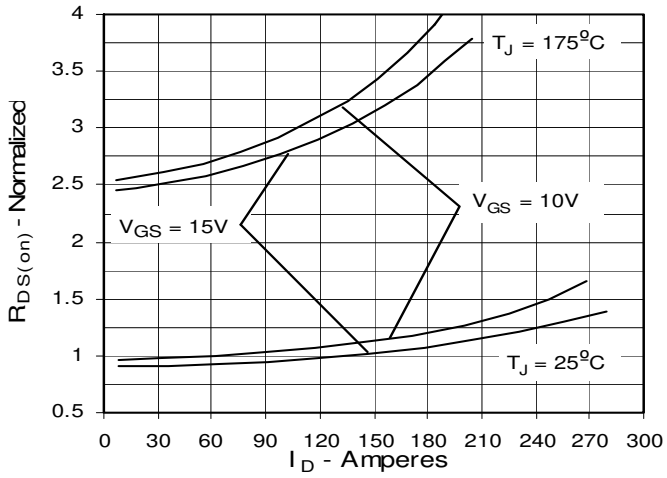


Fig. 6. Drain Current vs. Case Temperature

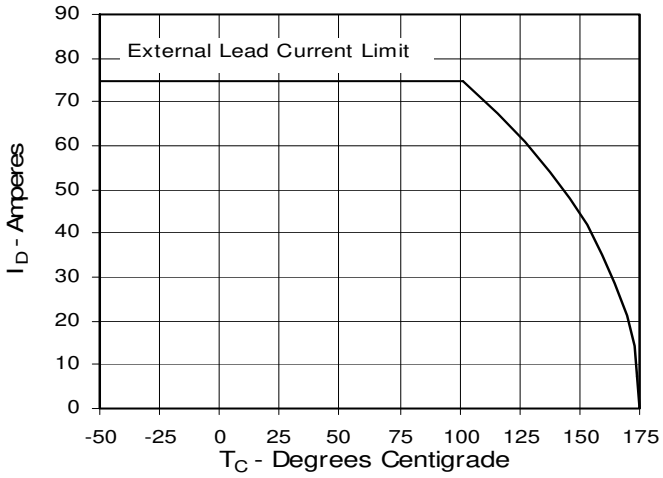


Fig. 7. Input Admittance

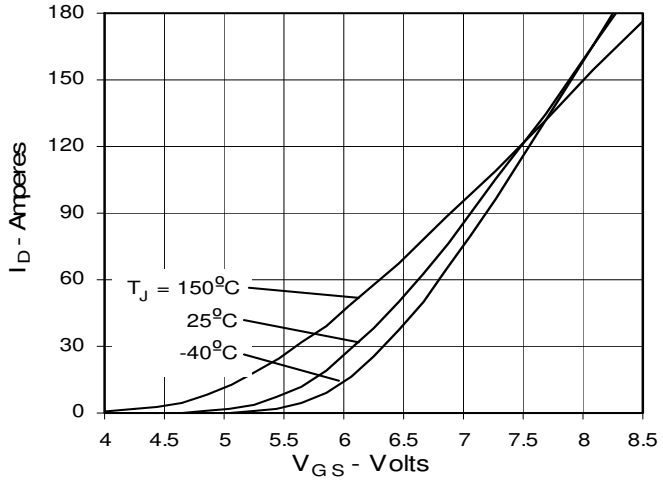


Fig. 8. Transconductance

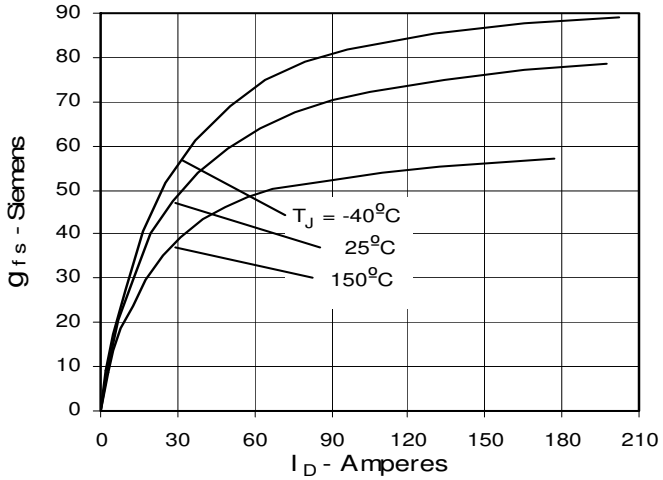


Fig. 9. Source Current vs. Source-To-Drain Voltage

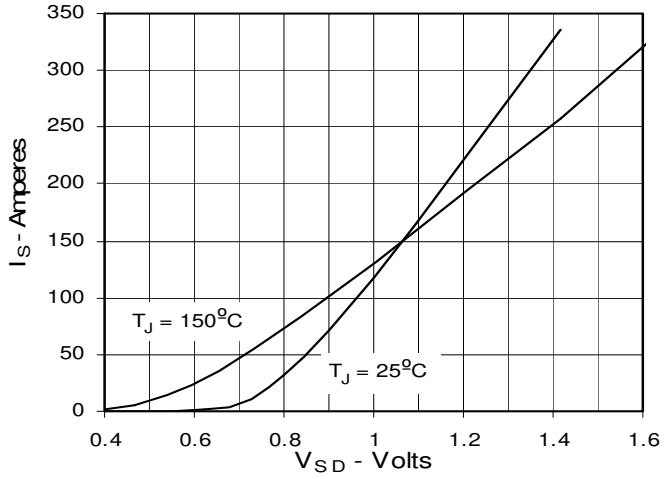


Fig. 10. Gate Charge

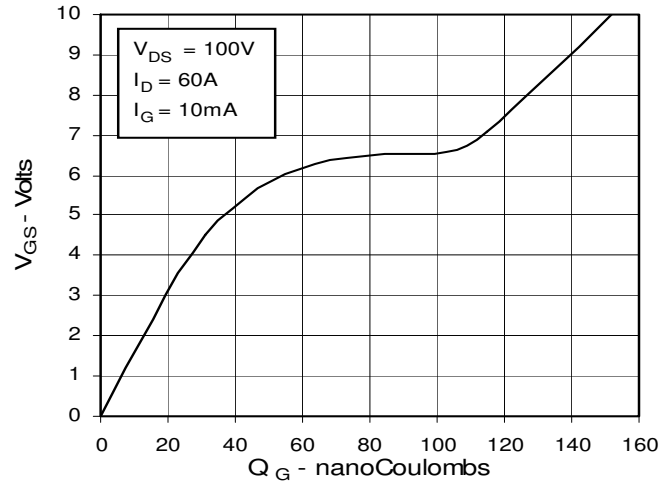


Fig. 11. Capacitance

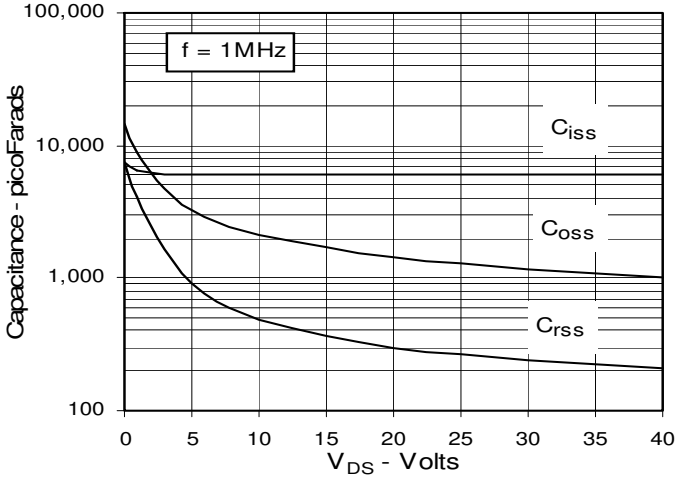


Fig. 12. Forward-Bias Safe Operating Area

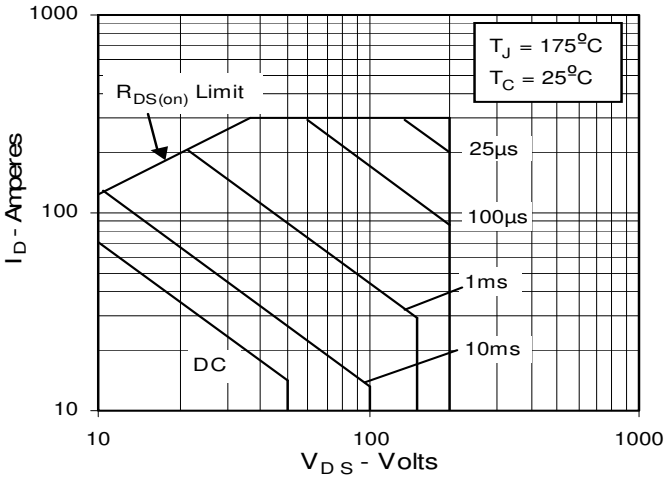


Fig. 13. Maximum Transient Thermal Resistance